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Part Number: [0739441007](#)
Status: **Active**
Overview: [hdm](#)
Description: 2.00mm (.079") Pitch HDM® Board-to-Board Backplane Header, Vertical, SMC, Solder Tail, Guide Pin Option, 144 Circuits

Documents:

[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)
[Product Specification PS-73670-9999 \(PDF\)](#)

Agency Certification

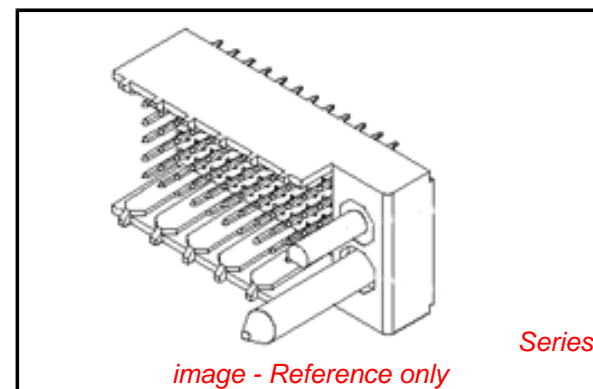
CSA LR19980
 UL E29179

General

Product Family Backplane Connectors
 Series [73944](#)
 Application Backplane
 Component Type PCB Header
 Overview [hdm](#)
 Product Name HDM®
 Style N/A

Physical

Circuits (Loaded) 144
 Circuits (maximum) 144
 Color - Resin Black, Natural
 Durability (mating cycles max) 250
 First Mate / Last Break No
 Flammability 94V-0
 Guide to Mating Part Yes
 Keying to Mating Part Yes
 Material - Metal Phosphor Bronze, Stainless Steel
 Material - Plating Mating Gold
 Material - Plating Termination Tin
 Material - Resin High Temperature Thermoplastic
 Number of Columns 24
 Number of Pairs Open Pin Field
 Number of Rows 6
 Orientation Vertical
 PC Tail Length (in) 0.079 In
 PC Tail Length (mm) 2.00 mm
 PCB Locator No
 PCB Retention None
 PCB Thickness Recommended (in) 0.098 In
 PCB Thickness Recommended (mm) 2.50 mm
 Packaging Type Tube
 Pitch - Mating Interface (in) 0.079 In
 Pitch - Mating Interface (mm) 2.00 mm
 Pitch - Term. Interface (in) 0.079 In
 Pitch - Term. Interface (mm) 2.00 mm
 Plating min: Mating (µin) 30
 Plating min: Mating (µm) 0.75
 Plating min: Termination (µin) 100
 Plating min: Termination (µm) 2.5
 Polarized to PCB No



EU RoHS

**ELV and RoHS
 Compliant**
**REACH SVHC
 Not Reviewed**
**Halogen-Free
 Status
 Not Reviewed**

China RoHS



**Need more information on product
 environmental compliance?**

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

[73944Series](#)

Mates With

[73632 HDM PLUS® Board-to-Board Daughtercard Receptacle](#). [73780 HDM® Board-to-Board Daughtercard Receptacle](#)

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description	Product #
HDM® Backplane	0621001400
Insertion Signal	
Contact Tool	
Extraction Tool	0621001000

Stackable	No
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole

Electrical

Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0818
Product Specification	PS-73670-9999
Sales Drawing	SD-73944-001

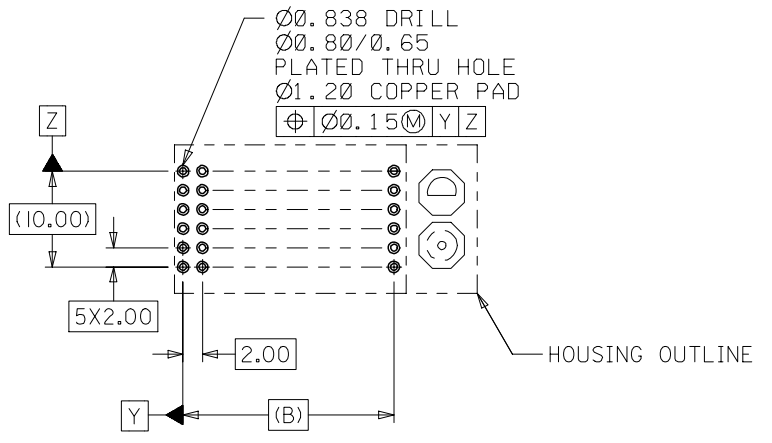
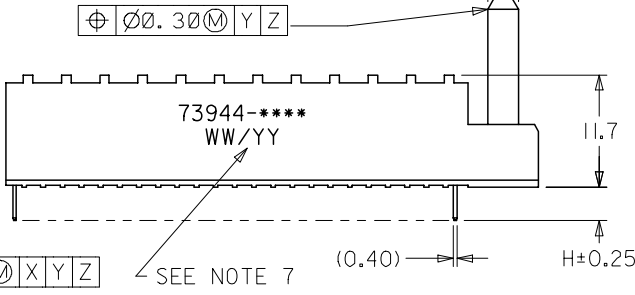
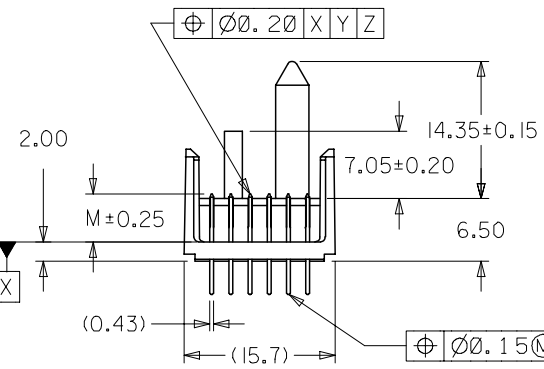
HDM and High Density Metric are trademarks of Amphenol Corporation

This document was generated on 05/14/2010

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NOTES:

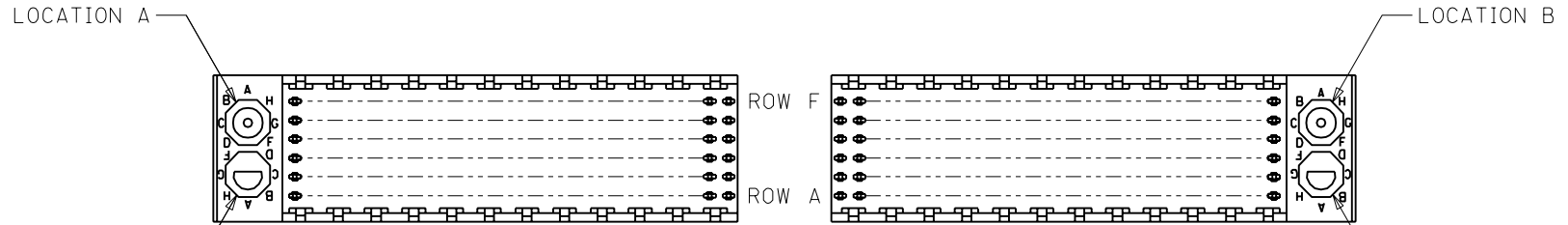
1. MATERIALS: HOUSING--LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, UL94V-0, COLOR: BLACK, TERMINAL: PHOSPHOR BRONZE.
2. FINISH: 0.75 MICROMETERS MINIMUM SELECTIVE GOLD (Au) IN MATING AREA 2.50 MICROMETERS MINIMUM SELECTIVE TIN (Sn) IN TAIL AREA NICKEL (Ni) UNDERPLATE OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73670-9999.
4. FOR MIXED CONTACT MATING LENGTHS, CONSULT FACTORY FOR AVAILABILITY.
5. SEE SHEET 2 FOR SPECIFIC MATERIAL NUMBERS.
6. PACKAGE PER PK-70873-0818.
7. PARTS MARKED WITH PART NUMBER AND DATE CODE, ON EITHER SIDE, APPROXIMATELY WHERE SHOWN.



PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN

2	A
1	G
SHT	REV

MODIFY FINISH NOTE EC NO: UCP2007-2259 DRWN:MSIBARRA 2007/03/13 CHKD:BBARKER 2007/03/21 APPR:SMILLER 2007/03/22	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION															
	▽=0 ▽=0	<table border="1"> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.05</td> <td>± ---</td> </tr> <tr> <td>1 PLACE</td> <td>± 0.10</td> <td>± ---</td> </tr> </table>		mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.05	± ---	1 PLACE	± 0.10	± ---	MM ONLY	2:1	METRIC	
		mm	INCH																		
	4 PLACES	± ---	± ---																		
3 PLACES	± ---	± ---																			
2 PLACES	± 0.05	± ---																			
1 PLACE	± 0.10	± ---																			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY: JB INGHAM DATE: 1998/01/14 CHECKED BY: SREED DATE: 1998/01/14 APPROVED BY: CBIXLER DATE: 1998/01/14	TITLE	SALES ASSY HDM BACKPLANE POLAR/GUIDE OPTION SOLDER TAIL VERSION																		
MATERIAL NO. SEE CHART	DOCUMENT NO. SD-73944-001	MOLEX INCORPORATED		SHEET NO. 1 OF 2																	



REF. MATERIAL NUMBER 73944-1009
 GUIDE PIN IS IN LOCATION A
 POLARIZING KEY IS IN LOCATION B, POSITION E

REF. MATERIAL NUMBER 73944-1008
 GUIDE PIN IS IN LOCATION B
 POLARIZING KEY IS IN LOCATION A, POSITION E

MATERIAL NUMBER ASSIGNMENT

73944- * * * *

NUMBER	CIRCUIT SIZE	DIM "A"	DIM "B"	DIM "H"
0	72	31.60	22.00	2.00
1	144	55.60	46.00	2.00
2	72	31.60	22.00	2.50
3	144	55.60	46.00	2.50
4	72	31.60	22.00	3.00
5	144	55.60	46.00	3.00
6	72	31.60	22.00	3.50
7	144	55.60	46.00	3.50

NUMBER	DIM "M"
0	5.00
1	5.50
2	6.00

NUMBER	GUIDE POST LOCATION	POLAR KEY POSITION
00	B	
01	A	A
02	B	B
03	A	C
04	B	D
05	A	E
06	B	F
07	A	G
08	B	H
09	A	
10	B	
11	A	
12	B	
13	A	
14	B	
15	A	
16	B	
17	A	
18	N/A	N/A

SEE SHEET 1
 EC No. U81577
 DRWN: BINGHAM 98/02/03
 CHK: REED 98/02/03
 APPR: BIXLER 98/02/03

MAJOR = 0
 CRITICAL = 0

DESCRIPTION
 REV A

QUALITY SYMBOLS

GENERAL TOLERANCES: (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	±0.	±.
3 PLACES	±0.	±.
2 PLACES	±0./N/A	±.
1 PLACE	±0./N/A	±.

ANGULAR: ± 1/2°

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

SCALE 2 : 1
 DESIGN UNITS mm INCH

DRAWN BY & DATE
 JBINGHAM 98/01/14

CHECKED BY & DATE
 SREED 98/01/14

APPROVED BY & DATE
 CBIXLER 98/01/14

CAD FILENAME
 S73944X2.DGN

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.

DIMENSIONS:
 mm INCH mm ONLY

SHT REV
 REVISE ON CAD ONLY

TITLE: SALES ASSY, HDM BACKPLANE
 POLAR/GUIDE OPTION
 SOLDER TAIL VERSION

MOLEX MOLEX INCORPORATED

MATERIAL NO. SEE CHART
 DRAWING NO. SD-73944-001
 SHEET NO. 2

SIZE B



Стандарт Электрон Связь

Мы молодая и активно развивающаяся компания в области поставок электронных компонентов. Мы поставляем электронные компоненты отечественного и импортного производства напрямую от производителей и с крупнейших складов мира.

Благодаря сотрудничеству с мировыми поставщиками мы осуществляем комплексные и плановые поставки широчайшего спектра электронных компонентов.

Собственная эффективная логистика и склад в обеспечивает надежную поставку продукции в точно указанные сроки по всей России.

Мы осуществляем техническую поддержку нашим клиентам и предпродажную проверку качества продукции. На все поставляемые продукты мы предоставляем гарантию .

Осуществляем поставки продукции под контролем ВП МО РФ на предприятия военно-промышленного комплекса России , а также работаем в рамках 275 ФЗ с открытием отдельных счетов в уполномоченном банке. Система менеджмента качества компании соответствует требованиям ГОСТ ISO 9001.

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С нами вы становитесь еще успешнее!

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